FID1 FID2 FID3 FID4 FID5 FID6

PCB Number: TIDA00230
PCB Rev: E1

PCB
LOGO
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Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

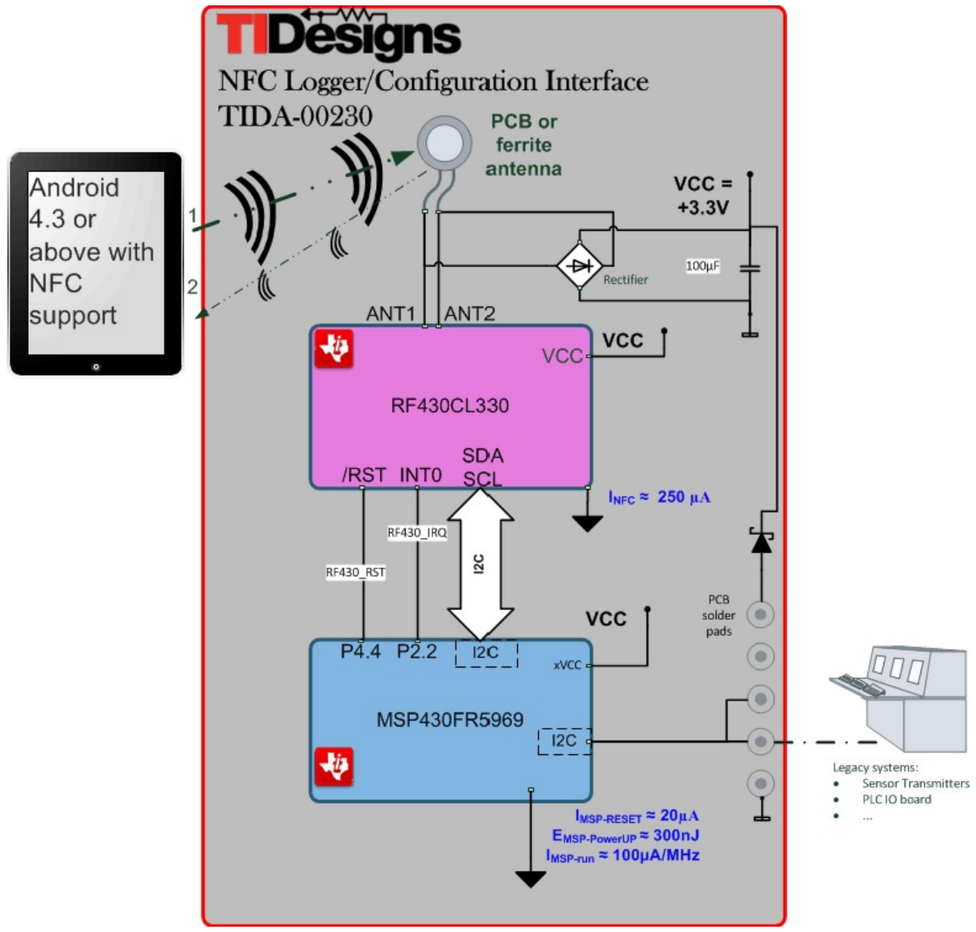
ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Number: TIDA00230	Rev: E1	Designed for: Public Release	Mod. Date: 7/22/2014
SVN Rev: Not in version control		Project Title: NFC Logger/Configuration sub-system	
Drawn By:		Sheet Title:	
Engineer: M. Chevrier		Assembly Variant: TIDA00230_Default	Sheet: 1 of 1
		File: TIDA00230 E1 Hardware_ANSI-B.SchDoc	Size: B
		Contact: http://www.ti.com/support	

TEXAS INSTRUMENTS
http://www.ti.com

Revision History	
Revision	Notes
E0	Creation



Number: TIDA00230	Rev: E1	Designed for: Public Release	Mod. Date: 6/16/2014
SVN Rev: Not in version control		Project Title: NFC Logger/Configuration sub-system	
Drawn By: M. Chevrier		Sheet Title: System Block Diagram	
Engineer: M. Chevrier		Assembly Variant: TIDA00230_Default	Sheet: 1 of 1
		File: TIDA00230 E1 Cover Sheet.SchDoc	Size: B
		Contact: http://www.ti.com/support	

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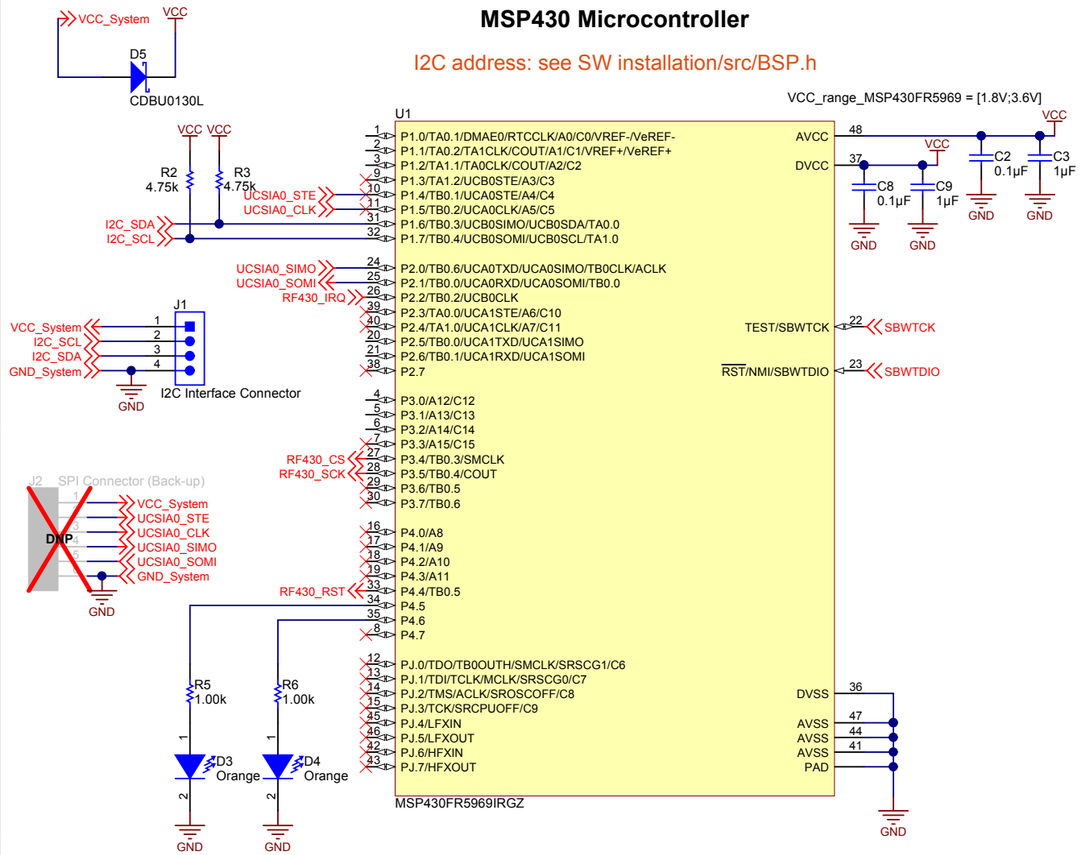
MSP430 Microcontroller

I2C address: see SW installation/src/BSP.h



RF430 Dynamic NFC Transponder

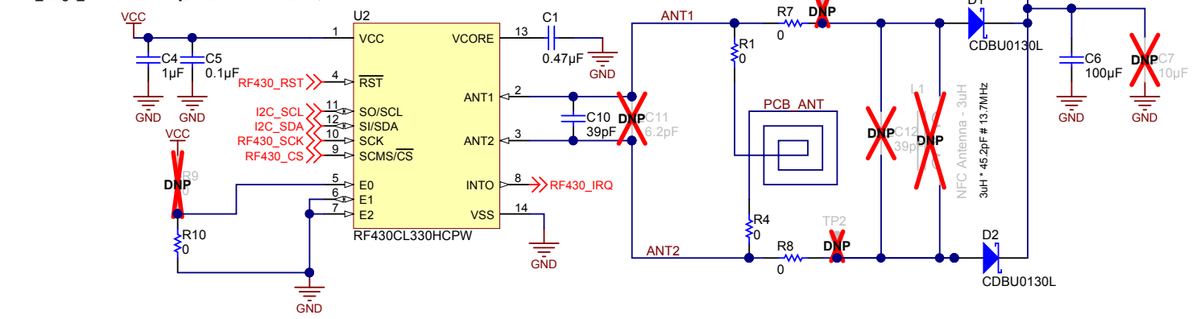
I2C Address =
0101000 or 0101001 (LSB set by E0)

VCC_range_RF430CL330 = [2V with NFC field or 3V;3.6V

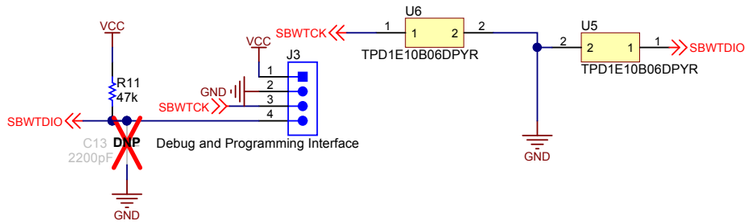
Default: R1,R4,R7,R8 mounted, L1, C12 not mounted
VCC will be limited to 3.6V by U2

Ferrite: PCB_ANT disconnected (R1, R4 not mounted), L1 mounted, C12 not mounted

SplitPowerRF: R1, R4, L1, C12 mounted, R7, R8 not mounted



SBW Interface & ESD Protection



Designed for: Public Release		Mod. Date: 6/16/2014	
Project Title: NFC Logger/Configuration sub-system			
Number: TIDA00230	Rev: E1	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: TIDA00230_Default	Sheet: 1 of 1
Drawn By: M. Chevrier		File: TIDA00230 E1.SchDoc	Size: B
Engineer: M. Chevrier		Contact: http://www.ti.com/support	

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